

# EPIC-KBS9

## Thermal Image Analysis Report

**Test Cause**

**For ATRF No.QE180301 Request**

Summary	<input type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input checked="" type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> <u>There are four temperature point marginal passed, the system works properly.</u>			
<b>Test Result Summary</b>				
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	4
Defect Unsolved	0	0	0	4

Issue date	QE Manager	Test Engineer
2018 / 03 / 07	KJ Wang	Ben Sun

## Sample Configuration & Quantity Under Test

- **Model name : EPIC-KBS9 A0.2**
- **CPU : Intel® Core™ i7-7700 CPU @ 3.60GHz**
- **Memory : Transcend DDR4L-2133 SO-DIMM 8GB \*2**
- **3.5" SATA HDD : Western Digital WD1600AAJS 160GB 3.5"HD**
- **BIOS : EKS9AM05**
- **Test Software : Windows 10 / Run PassMark Burn In Test 8.1 Pro**
- **Power : AT Power**
- **Heat Sink & Fan :**



# Thermal Image Analysis

1. Test Date: 2018-03-06

2. Test Product: EPIC-KBS9 A0.2

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.2.2 Model: DA100-13-1D

Date of Calibration: 2017/09/08

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 2017/11/23

Serial Number: 1051444

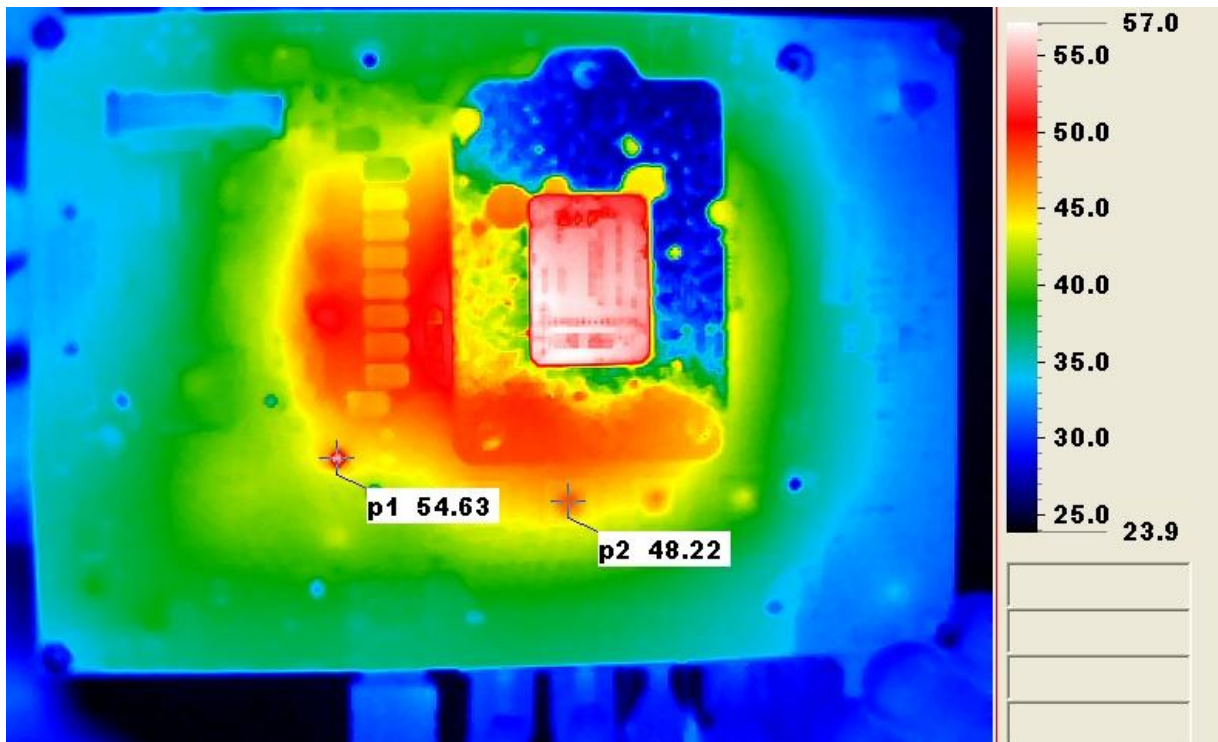
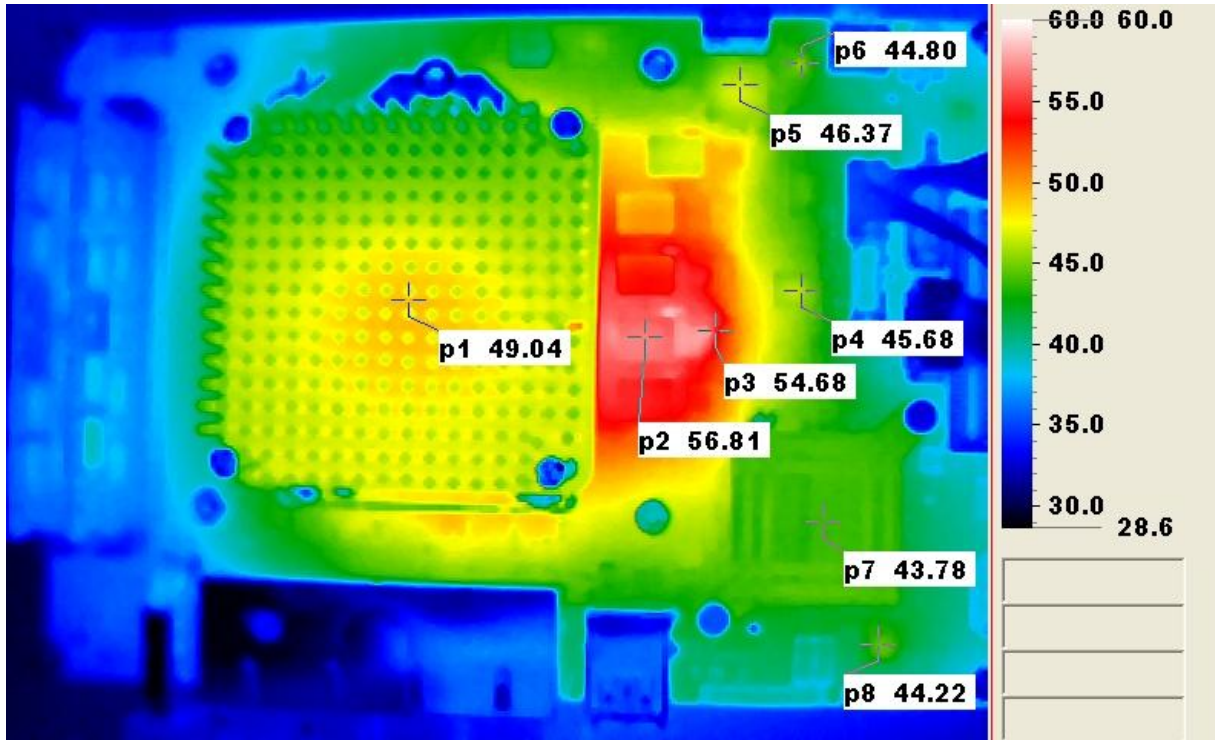
5. Test Condition:

Test by DA-100: 24.5°C with Heat Sink & Fan

6. Take Picture Time:

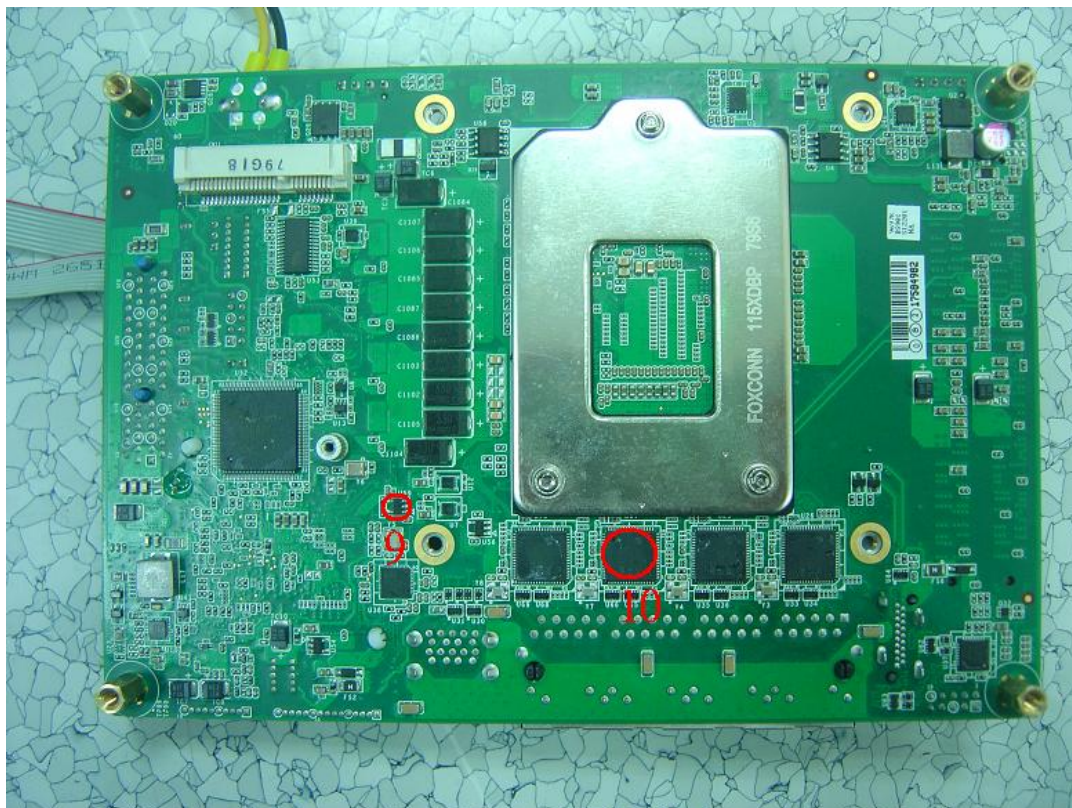
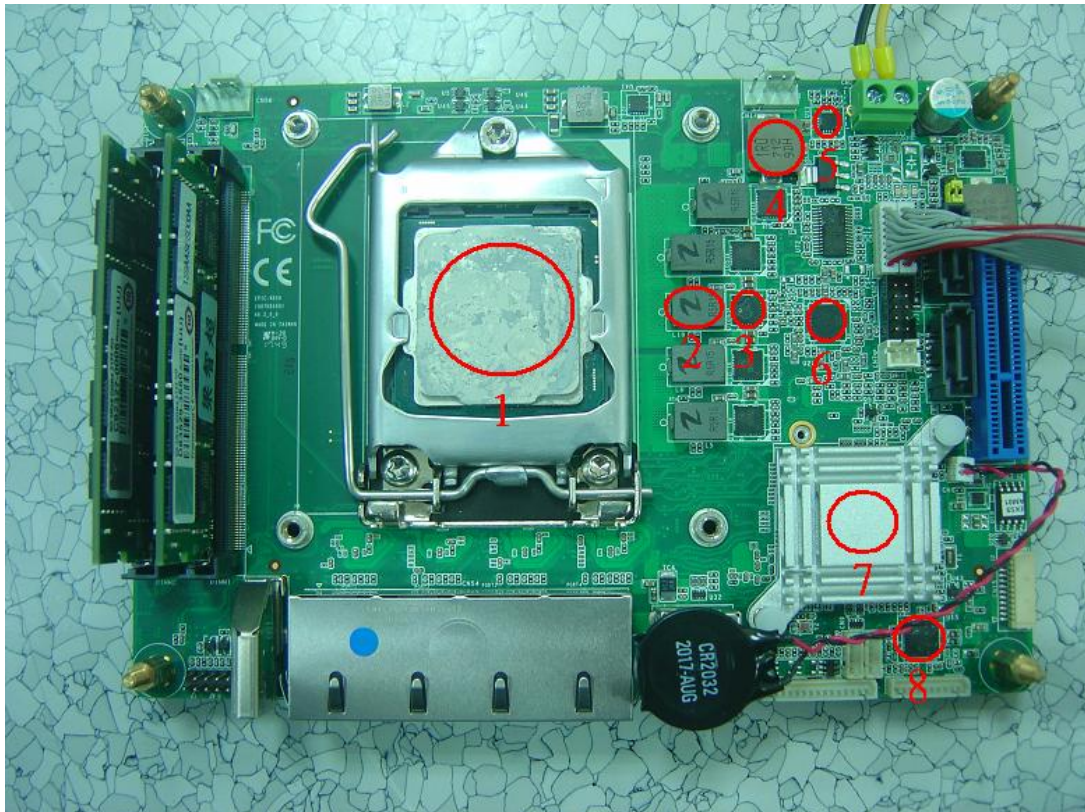
After power on 2 hours

**Temperature Profile Test:**  
**Component Side:**



### Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)		TPT(*3)	Note
				25.0°C	60°C		
1	CPU1	(TF)Intel 7th Core Processor.Kaby Lake-S.3.6Ghz, 8MB Cache.FCLGA1151.i7-7700	75	42.0	77.0	NOTE4	
2	L19	(TF)COIL.150nH.DCR=0.29mohm.Idc=53A.20%.2P.10.5*7*4.95mm.SMD.ZenithTek.ZPWA-107050R5-R15	150	46.8	81.8		
3	U106	(TF)IC.Integrated Driver and MOSFET.PQFN.31P.SMD.ON Semi.SCP302045MNTWG	150	46.5	81.5		
4	L3	(TF)COIL.1uH.25A.2.3mohm.20%.SMD.11.5*10.3*4mm.CY NTEC.PCME104T-1R0MS2R307	150	48.4	83.4		
5	U11	(TF)IC.Wide Input Voltage.Single Synchronous Step-Down QFN 16P.SMD.TI.TPS53219ARGTR	125	42.4	77.4		
6	U22	(TF)IC. Dual Output Controller.with Single SVID Interface CPU.for Applications.QFN 52P SMD ON NCP81243MNTXG	150	45.2	80.2		
7	U16	(TF)INTEL.CHIPSET.BGA837P.SMD.GL82Q170.SR2C5	108	47.5	82.5		
8	U15	(TF)IC.HDA Audio Codec.w/Class-D AMP.MQFN 48P.SMD REALTEK.ALC269Q-VC2-GR	85	43.1	78.1	NOTE4	
9	U67	(TF)IC.LDO.0.3V.300mA.SOT-23-5 5P.SMD.ANPEC APL5325BI-TRG	125	50.2	85.2		
10	U59	(TF)IC.PCI-E GigaBit Ethernet Chipset.QFN 64P.SMD Intel.WGI211AT	85	44.5	79.5	NOTE4	
11		RAM	85	39.3	74.3	NOTE4	

Note(\*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
  - "TAT" indicates the actual measured temperature under product specification.
  - "TPT" indicates the predicted temperature under 25°C working environmental.
  - Judgment Criteria:**
    - **Fail** :  $T_m > T_c + 5^\circ\text{C}$ ; The measured value is over specification plus margin.
    - **Margin** :  $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$ ; The measured value is within specification with margin.  
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
    - **Pass** :  $T_m < T_c - 10^\circ\text{C}$ ; The measured value is with safety margin.
  - RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.
4. Defect NO.